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Tender

## **Supply, Delivery and Installation of wafer dicing kit for NMIS**

University of Strathclyde

F02: Contract notice

Notice identifier: 2024/S 000-018851

Procurement identifier (OCID): ocds-h6vhtk-047100

Published 19 June 2024, 10:22am

### **Section I: Contracting authority**

#### **I.1) Name and addresses**

University of Strathclyde

McCance Building, 16 Richmond Street

Glasgow

G1 1XQ

#### **Email**

[jen.robertson@strath.ac.uk](mailto:jen.robertson@strath.ac.uk)

#### **Telephone**

+44 7811592949

#### **Country**

United Kingdom

#### **NUTS code**

UKM82 - Glasgow City

### **Internet address(es)**

Main address

<http://www.strath.ac.uk/>

Buyer's address

[https://www.publiccontractsscotland.gov.uk/search/Search\\_AuthProfile.aspx?ID=AA00113](https://www.publiccontractsscotland.gov.uk/search/Search_AuthProfile.aspx?ID=AA00113)

### **I.2) Information about joint procurement**

The contract is awarded by a central purchasing body

### **I.3) Communication**

The procurement documents are available for unrestricted and full direct access, free of charge, at

<https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/pts-host/public/pts/web/login.html>

Additional information can be obtained from the above-mentioned address

Tenders or requests to participate must be submitted electronically via

[https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do?\\_ncp=1718717323289.17229-1](https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do?_ncp=1718717323289.17229-1)

Electronic communication requires the use of tools and devices that are not generally available. Unrestricted and full direct access to these tools and devices is possible, free of charge, at

[https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do?\\_ncp=1718717323289.17229-1](https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do?_ncp=1718717323289.17229-1)

### **I.4) Type of the contracting authority**

Body governed by public law

### **I.5) Main activity**

Education

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## **Section II: Object**

### **II.1) Scope of the procurement**

#### **II.1.1) Title**

Supply, Delivery and Installation of wafer dicing kit for NMIS

Reference number

UOS-30411-2024

#### **II.1.2) Main CPV code**

- 31712330 - Semiconductors

#### **II.1.3) Type of contract**

Supplies

#### **II.1.4) Short description**

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

#### **II.1.5) Estimated total value**

Value excluding VAT: £1,000,000

#### **II.1.6) Information about lots**

This contract is divided into lots: Yes

Tenders may be submitted for all lots

## **II.2) Description**

### **II.2.1) Title**

Saw Dicing

Lot No

1

### **II.2.2) Additional CPV code(s)**

- 31712330 - Semiconductors

### **II.2.3) Place of performance**

NUTS codes

- UKM82 - Glasgow City

Main site or place of performance

University of Strathclyde

### **II.2.4) Description of the procurement**

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this sub-section of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 1 – Saw Dicing

**II.2.5) Award criteria**

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

**II.2.7) Duration of the contract, framework agreement or dynamic purchasing system**

Duration in months

18

This contract is subject to renewal

No

**II.2.10) Information about variants**

Variants will be accepted: No

**II.2.11) Information about options**

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

**II.2.13) Information about European Union Funds**

The procurement is related to a project and/or programme financed by European Union funds: No

**II.2) Description**

**II.2.1) Title**

Laser Dicing

Lot No

2

### **II.2.2) Additional CPV code(s)**

- 31712330 - Semiconductors

### **II.2.3) Place of performance**

NUTS codes

- UKM82 - Glasgow City

### **II.2.4) Description of the procurement**

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this sub-section of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 2 – Laser Dicing

### **II.2.5) Award criteria**

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

### **II.2.7) Duration of the contract, framework agreement or dynamic purchasing system**

Duration in months

18

This contract is subject to renewal

No

### **II.2.10) Information about variants**

Variants will be accepted: No

### **II.2.11) Information about options**

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

### **II.2.13) Information about European Union Funds**

The procurement is related to a project and/or programme financed by European Union funds: No

## **II.2) Description**

### **II.2.1) Title**

Scribe & Break

Lot No

3

### **II.2.2) Additional CPV code(s)**

- 31712330 - Semiconductors

### **II.2.3) Place of performance**

NUTS codes

- UKM82 - Glasgow City

#### **II.2.4) Description of the procurement**

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this sub-section of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 3 – Scribe & Break

#### **II.2.5) Award criteria**

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

#### **II.2.7) Duration of the contract, framework agreement or dynamic purchasing system**

Duration in months

18

This contract is subject to renewal

No

### **II.2.10) Information about variants**

Variants will be accepted: No

### **II.2.11) Information about options**

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

### **II.2.13) Information about European Union Funds**

The procurement is related to a project and/or programme financed by European Union funds: No

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## **Section III. Legal, economic, financial and technical information**

### **III.1) Conditions for participation**

#### **III.1.2) Economic and financial standing**

List and brief description of selection criteria

4B 1.2 Turnover

Bidders will be required to have the average yearly turnover to participate in the relevant lot (see below) This is to ensure the University is protected from any unforeseen financial risks that may impact the supplier or supply chain.

Lot 1 - GBP 600,000 for the last 3 (three) years

Lot 2 – GBP 2,000,000 for the last 3 (three) years

Lot 3 - GBP 1,600,000 for the last 3 (three) years

Minimum level(s) of standards possibly required

#### 4B.5.1- 4B5.3 Insurances

Insurance requirements are in line with levels identified in the UOS standard Terms and Conditions.

It is a requirement of this contract that bidders can hold or commit to obtain prior to the commencement of any subsequently awarded contract, the types of insurance indicated below:

The Contractor shall maintain in force with reputable insurers

Employer's (Compulsory) Liability Insurance = GBP 10m

Public and Product Liability Insurance = GBP 10m

Professional Risk Indemnity Insurance = GBP 1m

In respect of any one incident and unlimited as to numbers of claims

#### **III.1.3) Technical and professional ability**

List and brief description of selection criteria

#### 4C.1.2 Previous Experience

Bidders will be required to provide three (3) examples that demonstrate that they have the relevant experience to deliver the equipment as stated in the Contract Notice.

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## **Section IV. Procedure**

### **IV.1) Description**

#### **IV.1.1) Type of procedure**

Open procedure

#### **IV.1.8) Information about the Government Procurement Agreement (GPA)**

The procurement is covered by the Government Procurement Agreement: Yes

### **IV.2) Administrative information**

#### **IV.2.2) Time limit for receipt of tenders or requests to participate**

Date

22 July 2024

Local time

12:00pm

**IV.2.4) Languages in which tenders or requests to participate may be submitted**

English

**IV.2.6) Minimum time frame during which the tenderer must maintain the tender**

Duration in months: 4 (from the date stated for receipt of tender)

**IV.2.7) Conditions for opening of tenders**

Date

22 July 2024

Local time

12:00pm

Place

University of Strathclyde

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## **Section VI. Complementary information**

### **VI.1) Information about recurrence**

This is a recurrent procurement: No

### **VI.2) Information about electronic workflows**

Electronic ordering will be used

Electronic invoicing will be accepted

Electronic payment will be used

### **VI.3) Additional information**

The buyer is using PCS-Tender to conduct this ITT exercise. The Project code is 26821.  
For more information see:

<http://www.publiccontractsscotland.gov.uk/info/InfoCentre.aspx?ID=2343>

Community benefits are included in this requirement. For more information see:  
<https://www.gov.scot/policies/public-sector-procurement/community-benefits-in-procurement/>

A summary of the expected community benefits has been provided as follows:

Please see Procurement documents for full details

The buyer is using PCS-Tender to conduct this ITT exercise. The Project code is 26821.  
For more information see:

<http://www.publiccontractsscotland.gov.uk/info/InfoCentre.aspx?ID=2343>

Community benefits are included in this requirement. For more information see:  
<https://www.gov.scot/policies/public-sector-procurement/community-benefits-in-procurement/>

A summary of the expected community benefits has been provided as follows:

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A summary of the expected community benefits has been provided as follows:

Please see Procurement documents for full details

(SC Ref:769827)

#### **VI.4) Procedures for review**

##### **VI.4.1) Review body**

Glasgow Sheriff Court

Glasgow

Country

United Kingdom

##### **VI.4.3) Review procedure**

Precise information on deadline(s) for review procedures

An economic operator that suffers, or risks suffering, loss or damage attributable to a breach of duty under the Public Contracts (Scotland) Regulations

2015(SS12015/446) (as amended) may bring proceedings in the Sheriff Court or the Court of Session.